

N-Channel Super Junction Power MOSFET II

General Description

The series of devices use advanced super junction technology and design to provide excellent RDS(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

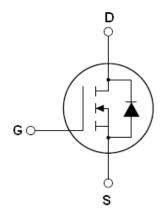
Features

- New technology for high voltage device
- Low on-resistance and low conduction losses
- small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ●ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

V _{DS}	650	٧
R _{DS(ON)MAX}	360	mΩ
I_{D}	11	A

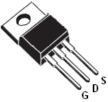


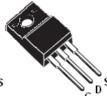
Schematic diagram

Package Marking And Ordering Information

Device	Device Package	Marking
NCE65R360D	TO-263	NCE65R360D
NCE65R360	TO-220	NCE65R360
NCE65R360F	TO-220F	NCE65R360F







TO-263

TO-220

TO-220F

Table 1. Absolute Maximum Ratings (T_C=25℃)

Parameter	Symbol	NCE65R360D NCE65R360	NCE65R360F	Unit
Drain-Source Voltage (V _{GS} =0V)	V _{DS}	650		V
Gate-Source Voltage (VDS=0V)	V _{GS}	±30		V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	11	11*	А
Continuous Drain Current at Tc=100°C	I _{D (DC)}	7	7*	А
Pulsed drain current (Note 1)	I _{DM (pluse)}	33	33*	Α
Maximum Power Dissipation(Tc=25°C)	P_{D}	121	32.7	W
Derate above 25°C		0.97	0.26	w/°C
Single pulse avalanche energy (Note2)	Eas	280		mJ
Avalanche current ^(Note 1)	I _{AR}	5.5		А
Repetitive Avalanche energy , t_{AR} limited by T_{jmax} (Note 1)	E _{AR}	0.5		mJ



Parameter	Symbol	NCE65R360D NCE65R360	NCE65R360F	Unit
Drain Source voltage slope, V _{DS} ≤480 V,	dv/dt	50	V/ns	
Reverse diode dv/dt, $V_{DS} \le 480 \text{ V,I}_{SD} < I_{D}$	dv/dt	15	V/ns	
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55+150		°C

^{*} limited by maximum junction temperature

Table 2. Thermal Characteristic

Parameter	Symbol	NCE65R360D NCE65R360	NCE65R360F	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R_{thJC}	1.03	3.82	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R_{thJA}	62	80	°C /W

Table 3. Electrical Characteristics (TA=25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
On/off states							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	650			V	
Zero Gate Voltage Drain Current(Tc=25°C)	I _{DSS}	V _{DS} =650V,V _{GS} =0V		0.05	1	μA	
Zero Gate Voltage Drain Current(Tc=125°C)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			100	μA	
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±30V,V _{DS} =0V			±100	nA	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	2.5	3	3.5	V	
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =7A		300	360	mΩ	
Dynamic Characteristics							
Forward Transconductance	g FS	V _{DS} = 20V, I _D = 7A		8		S	
Input Capacitance	C _{lss}	\/ -50\/\/ -0\/		1030		pF	
Output Capacitance	C _{oss}	V_{DS} =50V, V_{GS} =0V, F=1.0MHz		87		pF	
Reverse Transfer Capacitance	C _{rss}	F=1.UIVIDZ		4.5		pF	
Total Gate Charge	Qg	\/ -490\/ -444		23	40	nC	
Gate-Source Charge	Q _{gs}	V _{DS} =480V,I _D =11A, V _{GS} =10V		5.7		nC	
Gate-Drain Charge	Q_{gd}	VGS-10V		8		nC	
Intrinsic gate resistance	R_G	f = 1 MHz open drain		2		Ω	
Switching times							
Turn-on Delay Time	t _{d(on)}			9		nS	
Turn-on Rise Time	t _r	V_{DD} =380 V , I_{D} =5.5 A ,		4		nS	
Turn-Off Delay Time	$t_{d(off)}$	R_G =6.8 Ω , V_{GS} =10 V		40	65	nS	
Turn-Off Fall Time	t _f			4.5	8	nS	
Source- Drain Diode Characteristics							
Source-drain current(Body Diode)	I _{SD}	T _C =25°C			11	Α	
Pulsed Source-drain current(Body Diode)	I _{SDM}	1 _C -25 C			33	Α	
Forward on voltage	V_{SD}	Tj=25°C,I _{SD} =11A,V _{GS} =0V		0.9	1.2	V	
Reverse Recovery Time	t _{rr}			245		nS	
Reverse Recovery Charge	Q _{rr}	Tj=25°C,I _F =11A,di/dt=100A/μs		2.4		uC	
Peak Reverse Recovery Current	I _{rrm}			20		Α	

Notes: 1.Repetitive Rating: Pulse width limited by maximum junction temperature

^{2.} Tj=25°C,VDD=50V,VG=10V, R_G =25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

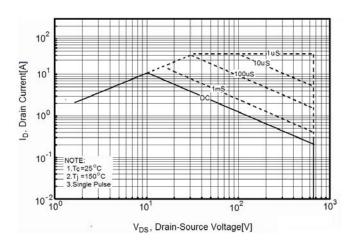


Figure 2. Safe operating area for TO-220F

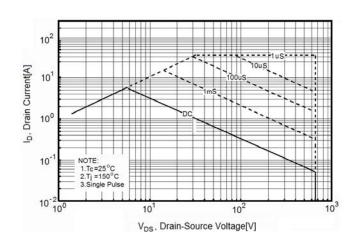


Figure3. Source-Drain Diode Forward Voltage

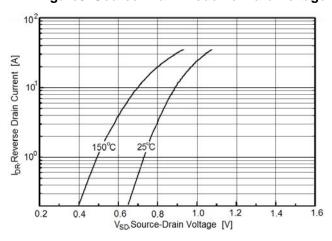


Figure 4. Output characteristics

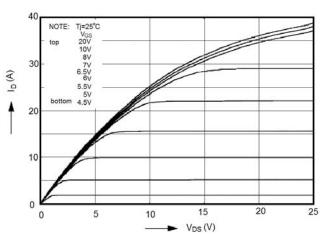


Figure 5. Transfer characteristics

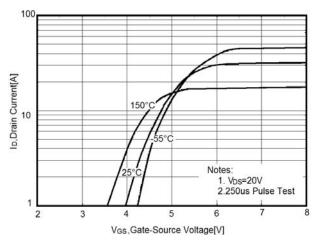


Figure 6. Static drain-source on resistance

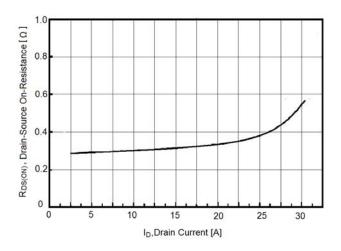




Figure 7. R_{DS(ON)} vs Junction Temperature

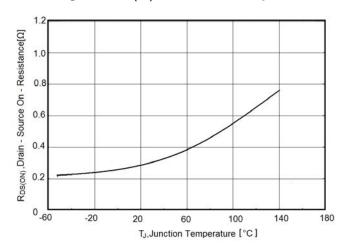


Figure 8. BV_{DSS} vs Junction Temperature

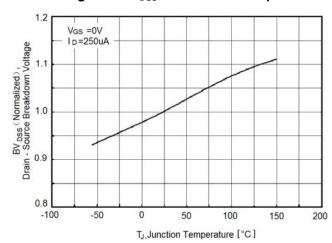


Figure 9. Maximum I_D vs Junction Temperature

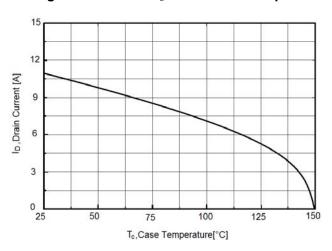


Figure 10. Gate charge waveforms

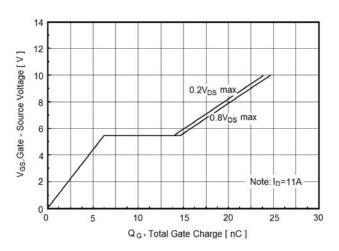


Figure11. Capacitance

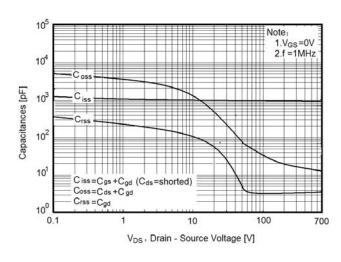


Figure 12. Transient Thermal Impedance

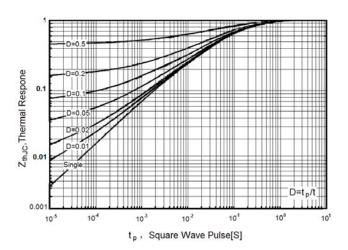
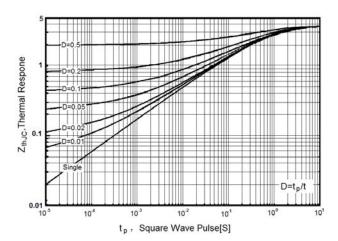




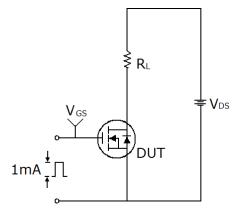
Figure 13. Transient Thermal Impedance for TO-220F

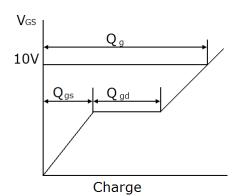




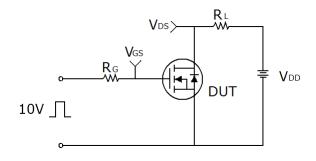
Test circuit

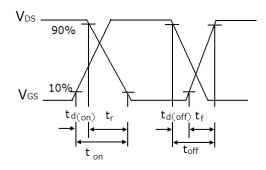
1) Gate charge test circuit & Waveform



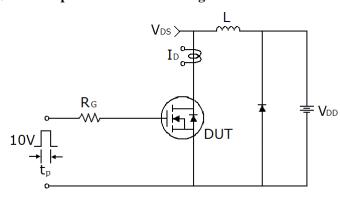


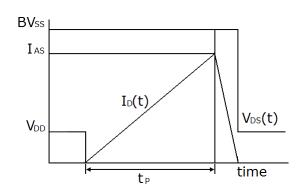
2) Switch Time Test Circuit:





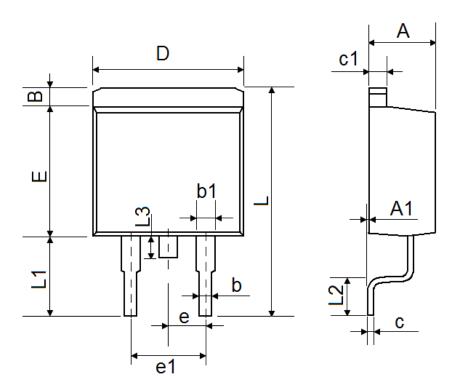
3) Unclamped Inductive Switching Test Circuit & Waveforms

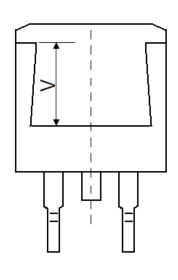






TO-263-2L Package Information

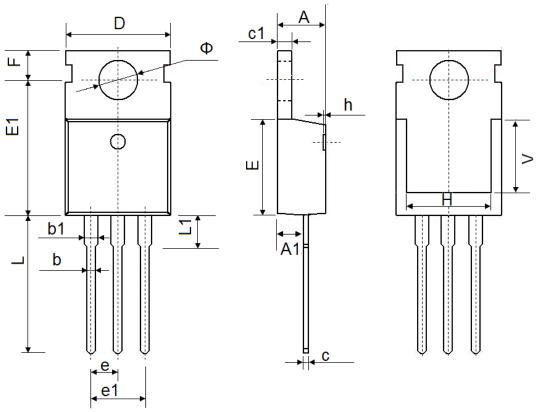




Ob. al	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	4.470	4.670	0.176	0.184	
A1	0.000	0.150	0.000	0.006	
В	1.170	1.370	0.046	0.054	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.310	0.530	0.012	0.021	
c1	1.170	1.370	0.046	0.054	
D	10.010	10.310	0.394	0.406	
E	8.500	8.900	0.335	0.350	
е	2.540	TYP.	0.100	TYP.	
e1	4.980	5.180	0.196	0.204	
L	15.050	15.450	0.593	0.608	
L1	5.080	5.480	0.200	0.216	
L2	2.340	2.740	0.092	0.108	
L3	1.300	1.700	0.051	0.067	
V	5.600	5.600 REF 0.220 REF		REF	



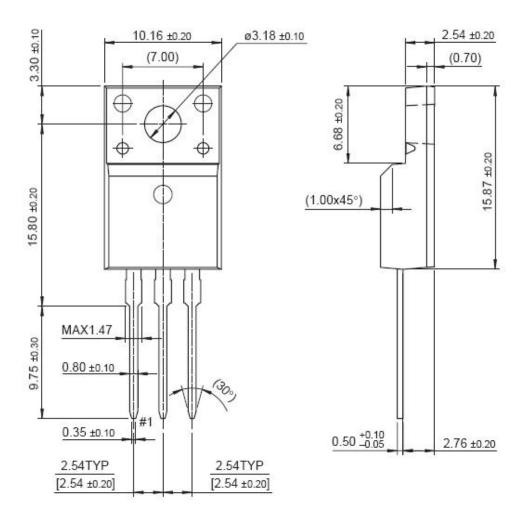
TO-220-3L-C Package Information

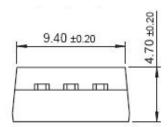


Oh. a l	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	4.400	4.600	0.173	0.181	
A1	2.250	2.550	0.089	0.100	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.330	0.650	0.013	0.026	
c1	1.200	1.400	0.047	0.055	
D	9.910	10.250	0.390	0.404	
E	8.9500	9.750	0.352	0.384	
E1	12.650	12.950	0.498	0.510	
е	2.540	2.540 TYP.		TYP.	
e1	4.980	5.180	0.196	0.204	
F	2.650	2.950	0.104	0.116	
Н	7.900	8.100	0.311	0.319	
h	0.000	0.300	0.000	0.012	
L	12.900	13.400	0.508	0.528	
L1	2.850	3.250	0.112	0.128	
V	7.500 REF.		0.295 REF.		
Ф	3.400	3.800	0.134	0.150	



TO-220F Package Information





Dimensions in Millimeters



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